


Full Material Declaration for attached parts list

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	<p>Diotec Semiconductor AG DUNS number: 330866844 -, Kreuzmattenstr. 4, Heitersheim, 79423, Germany Declarations authorised by: Udo Steinebrunner, Product Manager, -</p>
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Declaration effective from: 02 January 2015 [Approved on 07 May 2026, 08:58 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	3.8%	Silicon	7440-21-3	100%
Die attach	Lead and Lead alloys	4.77%	Silver	7440-22-4	2.5%
			Tin	7440-31-5	5%
			Lead EU RoHS Exemption 7(a) Exempt from other regulatory requirements Exempt from other regulatory requirements	7439-92-1	92.5%
Encapsulation	EP (Epoxy resin)	50.29%	Carbon black	1333-86-4	0.5%
			Magnesium oxide (Mg(OH) ₂)	1309-42-8	5%
			Phenol, polymer with formaldehyde	9003-35-4	10%
			Epoxy resin 89	26335-32-0	12%
			Quartz sand	60676-86-0	72.5%
Leadfinish	Tin plating	0.62%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	40.52%	Copper	7440-50-8	100%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
TO-269AA/MiniDIL (EB) H-free	Bridge Rectifier Dual Inline	0.077	g

